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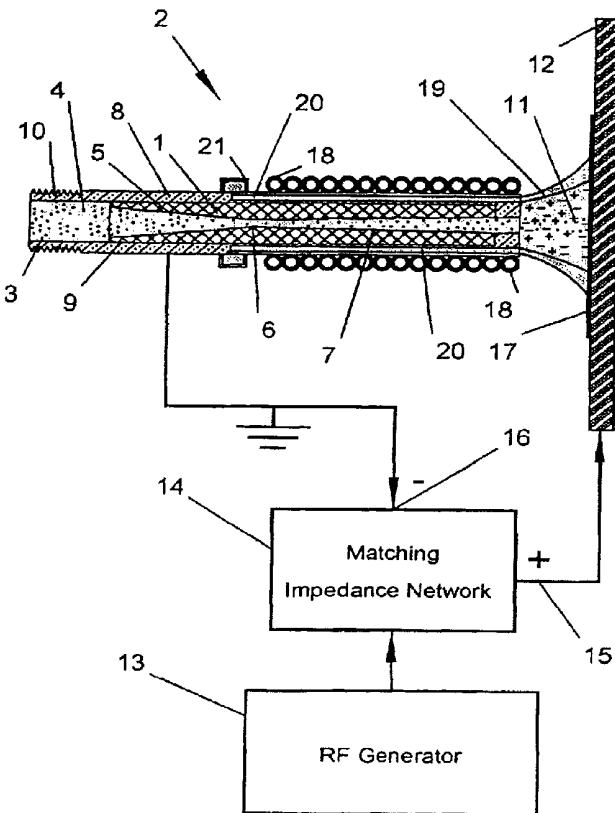
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(54) Title: A APPARATUS AND PROCESS FOR SOLID-STATE DEPOSITION AND CONSOLIDATION OF HIGH VELOCITY POWDER PARTICLES USING THERMAL PLASTIC DEFORMATION



(57) Abstract: Apparatus and process for solid-state deposition and consolidation of powder particles entrained in a subsonic or sonic gas jet onto the surface of an object. Under high velocity impact and thermal plastic deformation, the powder particles adhesively bond to the substrate and cohesively bond together to form consolidated materials with metallurgical bonds.



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